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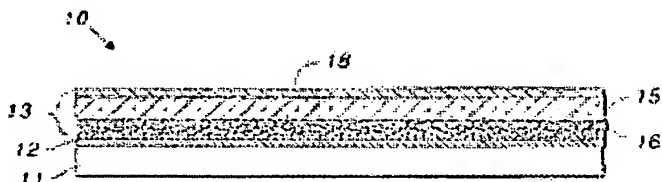
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Abstract of corresponding document: **US6445128**

EL panels are made with PVDF/HFP copolymer resin binder, in substantially an un-crosslinked form, with DMAC solvent and/or other higher boiling point solvents/latent solvents/extenders. The resin binder is characterized by a melt viscosity of 1.0-8.5 kP using an industry standard test (ASTM D3835).



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